



ERS AirCool 3 (AC3) systems certified according to international safety standards

MUNICH – July 12, 2012 - ERS electronic GmbH, technology leader in the market for Thermal Wafer Chucks for use in semiconductor production, has announced today that its AirCool 3 wafer thermal test system has successfully passed all tests associated with the applicable safety standards from Underwriters Laboratories (UL), International Electrotechnical Commission (IEC) and Canadian Standards Association (CSA).

The tests, conducted by TÜV Süd (Munich, Germany) and TÜV Süd USA (Peabody, MA, USA) certify that the ERS models for thermal wafer test of 150mm, 200mm, and 300mm wafers as well as the ERS AC3 Package Level Product Line meet the strict safety requirements for laboratory equipment involved in the heating of materials. The equipment has been certified according to UL 61010-1:2004, IEC 61010-2-010:2003, CAN/CSA-C22.2 No. 61010-1:2004 and CAN/CSA-C22.2 No. 61010-2-010:2004. These certificates are required by end users of test equipment containing the ERS products in the semiconductor manufacturing industry worldwide.

"Our systems are renowned for their performance, reliability and flexibility in thermal wafer probing throughout the semiconductor industry", said Klemens Reitingner, CEO of ERS electronic GmbH. "These TÜV certifications do not only confirm the high level of quality and safety designed into our products - to our knowledge, no other manufacturer of thermal chucks has all of these certifications for one product."

Thermal wafer chuck systems are a strategic part of the semiconductor production. They enable manufacturers to perform electrical tests on the wafer before the ICs are separated and packaged. Devices that would fail later in the process can be removed before the devices undergo the expensive process of packaging, thereby saving considerable manufacturing costs. The system offers very small footprint - and in some cases essentially zero footprint - for the associated chilling unit plus the capability to test power-dissipating semiconductor devices. Since it uses air instead of a liquid coolant, the AirCool3 offers unmatched reliability and unbeatably low cost of ownership.

For further information visit www.ers-gmbh.com

About ERS electronic GmbH:

ERS electronic GmbH, located near Munich, has been providing the most innovative thermal test solutions to the semiconductor industry for over 40 years. The best known products are its fast-ramping and precise low-noise thermal chuck systems (-65°C to +500°C) for analytical, parametric and wafer sort probing up to 300mm. ERS also designs and builds stand-alone thermal-forcing systems and custom production tools for special applications. ERS invented the AirCool, AirCoolplus and PowerSense thermal chuck systems that have been fully integrated into all major manual, semi- and full automatic wafer probers.

Press contact: Timothy K. Göbel - Brand+Image - +49 8143 99 268 34 - www.brandandimage.de